

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): TAKAHASHI et al

Serial No.: TBD

Filed: June 25, 2003

For: Solvent-Free Thermosetting Resin Composition,
Process For Producing The Same, And Product
Therefrom

PRELIMINARY AMENDMENT

Mail Stop
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

June 25, 2003

Sir:

Please amend the above-identified application, prior to examination thereof, as

follows:

IN THE SPECIFICATION:

Page 1, between the title and the heading "BACKGROUND OF THE
INVENTION" (that is, between lines 3 and 5), please add the following new
paragraph:

--This application is a Divisional application of Application No. 10/182,181, filed
July 25, 2002, which is a National Stage Application filed under 35 USC §371 of
International (PCT) Application No. PCT/JP00/00507, filed January 28, 2000. The
contents of Application No. 10/182,181, filed July 25, 2002, are incorporated herein
by reference in their entirety.--